

Device Embedding assembly technology - Part 2-602:
Guideline for stacked electronic module - Evaluation
method of inter-module electrical connectivity

EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

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English Version

Device embedding assembly technology - Part 2-602: Guideline
for stacked electronic module - Evaluation method of inter-
module electrical connectivity
(IEC 62878-2-602:2021)

Techniques d'assemblage avec appareil(s) intégré(s) -
Partie 2-602: Lignes directrices pour un empilement de
modules électroniques - Méthode d'évaluation de la
connectivité électrique entre modules
(IEC 62878-2-602:2021)

Montageverfahren für eingebettete Bauteile - Teil 2-602:
Leitfaden für gestapelte Elektronikmodule - Verfahren zur
Beurteilung der elektrischen Verbindungsfähigkeit zwischen
den Modulen
(IEC 62878-2-602:2021)

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European foreword

The text of document 91/1663/CDV, future edition 1 of IEC 62878-2-602, prepared by IEC/TC 91 “Electronics assembly technology” was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62878-2-602:2021.

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

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NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194-2	-	Printed boards design, manufacture and-assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies		-

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Device embedding assembly technology –
Part 2-602: Guideline for stacked electronic module – Evaluation method of
inter-module electrical connectivity**

**Techniques d'assemblage avec appareil(s) intégré(s) –
Partie 2-602: Lignes directrices pour un empilement de modules électroniques –
Méthode d'évaluation de la connectivité électrique entre modules**



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INTERNATIONAL
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INTERNATIONALE

ICS 31.180; 31.190

ISBN 978-2-8322-9894-7

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

DEVICE EMBEDDING ASSEMBLY TECHNOLOGY –

**Part 2-602: Guideline for stacked electronic module –
Evaluation method of inter-module electrical connectivity**

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International Standard IEC 62878-2-602 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1663/CDV	91/1720/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

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INTRODUCTION

High-end servers, network systems and smart phones have been driving the electronic assembly technologies for the last couple of decades. Any applications to enable the “Internet of Things” (aka IoT) require new electronic assembly technologies to achieve small size, low energy consumption and robust security in a cost-effective way.

This document is one of a series of guidelines for stacked electronic modules.

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